

性能指标	典型值	典型值	典型值	方向	单位	条件	测试方法
	[1] RO4725JXR	[1] RO4730JXR	[1] RO4730G3				
介电常数, ϵ_r 制造过程	2.55 ± 0.05	3.00 ± 0.05	3.00 ± 0.05	Z		10 GHz/23°C	IPC-TM-650, 2.5.5.5
[3] 介电常数, ϵ_r 设计	2.64	2.98	2.98	Z		1.7 GHz - 5 GHz	差相长度法
损耗因子	0.0026	0.0027	0.0029	Z		10 GHz/23°C	IPC-TM-650, 2.5.5.5
	0.0022	0.0023	0.0023			2.5 GHz	
TCDk	+34	+32	+26	Z	ppm/°C	-50°C to 150°C	IPC-TM-650, 2.5.5.5
体积电阻率 (0.030")	2.16 X 10 ⁸	5.96 X 10 ⁸	4.78 x 10 ⁸		MΩ · cm	COND A	IPC-TM-650, 2.5.17.1
表面电阻率 (0.030")	4.8 X 10 ⁷	1.68 X 10 ⁸	2.78 x 10 ⁸		MΩ	COND A	IPC-TM-650, 2.5.17.1
PIM [2]	-166	-164	-165		dBc	50 ohm 0.060"	43dBm 1900MHz
电气强度 (0.030")	630	721	762	Z	V/mil		IPC-TM-650, 2.5.6.2
挠曲强度	MD	121 (17.5)	167 (24.2)	209 (30.3)	MPa (kpsi)	RT	ASTM D790
	CMD	92 (13.3)	135 (19.6)	152 (22.1)			
尺寸稳定性	<0.4	<0.4	<0.4	X,Y	mm/m	蚀刻后 +E2/150°C	IPC-TM-650, 2.4.39A
热膨胀系数	13.9	11.3	13.7	X	ppm/°C	-55 TO 288°C	IPC-TM-650, 2.1.24
	19.0	13.5	14.7	Y			
	25.6	21.1	30.3	Z			
热导率	0.38	0.49	0.42	Z	W/mK°	50°C	ASTM D5470
吸水率	0.24%	0.14%	0.15%		%	48/50	IPC-TM-650 2.6.2.1 ASTM D570
Tg	>280	>280	>280		°C		IPC-TM-650 2.4.24
Td	439	443	417		°C		ASTM D3850
密度	1.27	1.53	1.58		gm/cm ³		ASTM D792
铜箔剥离强度	8.5	8.4	5.0		pli	1 oz LoPro EDC	IPC-TM-650 2.4.8
可燃性	N/A	N/A	是				UL94
无铅焊接兼容性	是	是	是				

Standard Thicknesses			Standard Panel Sizes:		Standard Copper Cladding
RO4725JXR	RO4730JXR	RO4730G3			
LoPro Copper 0.0307" (0.780mm) 0.0607" (1.542mm)	LoPro Copper 0.0207" (0.526mm) 0.0307" (0.780mm) 0.0407" (1.034mm) 0.0607" (1.542mm)	LoPro Copper 0.0057" (0.145mm) 0.0107" (0.272mm) 0.0207" (0.526mm) 0.0307" (0.780mm) 0.0407" (1.034mm) 0.0607" (1.542mm)	ED Copper 0.0200" (0.508mm) 0.0300" (0.762mm) 0.0400" (1.016mm) 0.0500" (1.270mm) 0.0600" (1.524mm)	12" X 18" (305 X 457 mm) 24" X 18" (610 X 457 mm) 24" X 36" (610 X 915 mm) 48" X 36" (1.224m X 915mm) Larger sizes may be available	LoPro Reverse Treated EDC Foil ½ oz (18µm), 1 oz (35µm) Standard EDC (RO4730G3 only) ½ oz (18µm), 1 oz (35µm)